

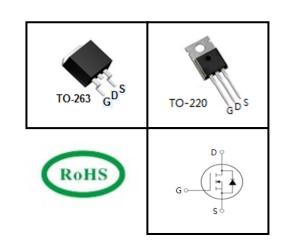
80V N-Channel Trench MOSFET

FEATURES

- High Density Cell Design for Ultra Low Rdson
- Fully Characterized Avalanche Voltage and Current
- Good Stability with High E_{AS}
- Excellent Package for Good Heat Dissipation

APPLICATIONS

- Power Switching Application
- Hard Switched and High Frequency Circuits
- Uninterruptible Power Supply



Device Marking and Package Information			
Device	Package	Marking	
TTB145N08A	TO-263	145N08A	
TTP145N08A	TO-220	145N08A	

Absolute Maximum Ratings T _C = 25°C, unless otherwise noted			
Parameter	Symbol	Value	Unit
Drain-Source Voltage (V _{GS} = 0V)	V _{DSS}	82	V
Continuous Drain Current	I _D	145	А
Pulsed Drain Current (note1)	I _{DM}	580	А
Gate-Source Voltage	V _{GSS}	±20	V
Single Pulse Avalanche Energy (note2)	E _{AS}	271	mJ
Avalanche Current	I _{AS}	42.5	А
Power Dissipation (T _C = 25°C)	P _D	272.7	W
Operating Junction and Storage Temperature Range	T_J,T_stg	-55~+175	°C

Thermal Resistance			
Parameter	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case	R _{thJC}	0.55	°C/W
Thermal Resistance, Junction-to-Ambient	R _{thJA}	62.5	°C/VV

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			Value			
Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static				'	•	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0V, I_D = 250\mu A$	82			V
Zoro Cata Valtago Proin Current		$V_{DS} = 82V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = 82V, V_{GS} = 0V, T_{J} = 150^{\circ}C$			100	μΑ
Gate-Source Leakage	I _{GSS}	$V_{GS} = \pm 20V$			±100	nA
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	3	4	V
Drain-Source On-Resistance (Note3)	R _{DS(on)}	$V_{GS} = 10V, I_D = 30A$		4.8	5.9	mΩ
Forward Transconductance (Note3)	g _{fs}	$V_{DS} = 5V, I_{D} = 20A$		36		S
Dynamic						
Input Capacitance	C _{iss}	V _{GS} = 0V,		8200		
Output Capacitance	C _{oss}	$V_{DS} = 40V$,		416		pF
Reverse Transfer Capacitance	C _{rss}	f = 1.0MHz		300		
Total Gate Charge	Q_g	$V_{DD} = 40V, I_{D} = 20A,$ $V_{GS} = 10V$		160		
Gate-Source Charge	Q_{gs}			30		nC
Gate-Drain Charge	Q_{gd}			35		
Turn-on Delay Time	t _{d(on)}			24		
Turn-on Rise Time	t _r	$V_{DD} = 40V$, $I_D = 20A$, $R_G = 2.5\Omega$		45		20
Turn-off Delay Time	t _{d(off)}			79		ns
Turn-off Fall Time	t _f			30		
Drain-Source Body Diode Characteris	stics					
Continuous Body Diode Current	I _s	T _C = 25°C			145	۸
Pulsed Diode Forward Current	I _{SM}				580	Α
Body Diode Voltage	V _{SD}	$T_J = 25^{\circ}C$, $I_{SD} = 20A$, $V_{GS} = 0V$			1.2	V
Reverse Recovery Time	t _{rr}	I _F = 20A, di _F /dt = 100A/μs		50		ns
Reverse Recovery Charge	Q _{rr}			110		nC

Notes

- 1. Repetitive Rating: Pulse Width limited by maximum junction temperature
- 2. V_{DD} = 50V, R_G = 25 Ω , Starting T_J = 25 $^{\circ}$ C
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 1%



Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted



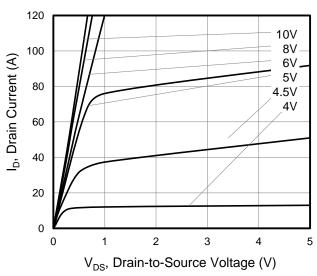


Figure 2. Transfer Characteristics

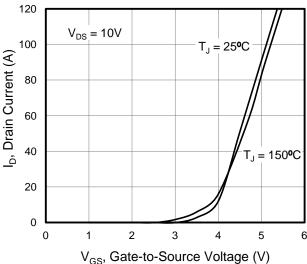


Figure 3. On-Resistance vs. Drain Current

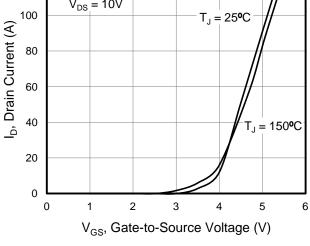
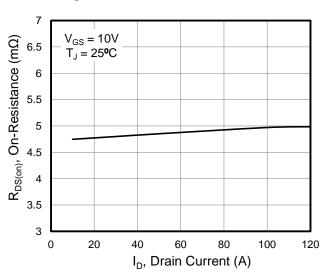


Figure 4. Capacitance



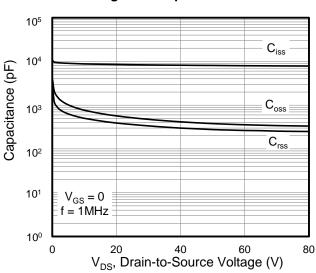
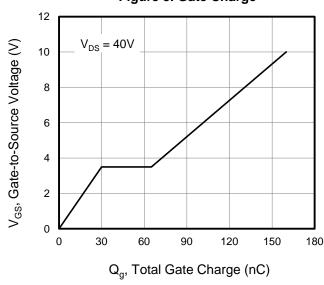
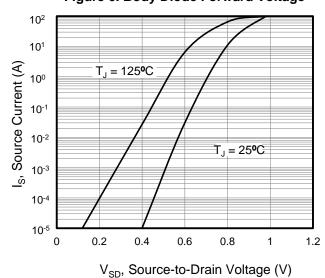


Figure 5. Gate Charge

Figure 6. Body Diode Forward Voltage





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Typical Characteristics $T_J = 25^{\circ}C$, unless otherwise noted

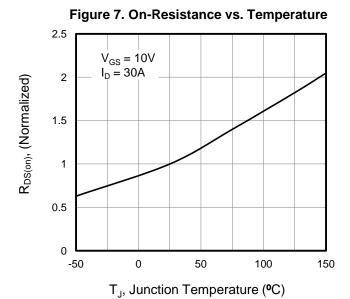


Figure 8. Threshold Voltage vs. Temperature

1
0.5
0.5 $I_D = 250\mu A$ -1
-1.5
-50
0
50
100
150
T_J, Junction Temperature (°C)

Figure 9. Breakdown voltage vs. Junction Temperature

1.3 $I_D = 250 \mu A$ 1.2 $(SSO)_{MB}$ 0.9

0.8

-50

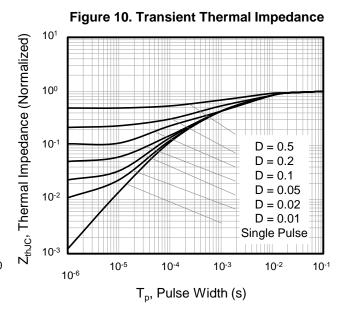
0

50

100

150

T_J, Junction Temperature (°C)



 10^{3} 10^{2} I_D, Drain Current(A) 10¹ 10⁰ = 10us = 100us 10-1 = 1ms = 10msĎС 10-2 10⁻¹ **10**0 10¹ 10² 10³

V_{DS}, Drain-Source Voltage(V)

Figure 11. Safe operation area for



Figure A: Gate Charge Test Circuit and Waveform

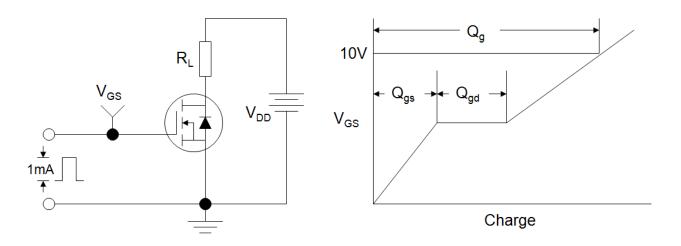


Figure B: Resistive Switching Test Circuit and Waveform

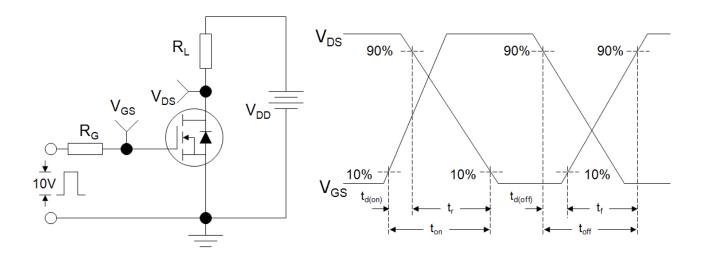
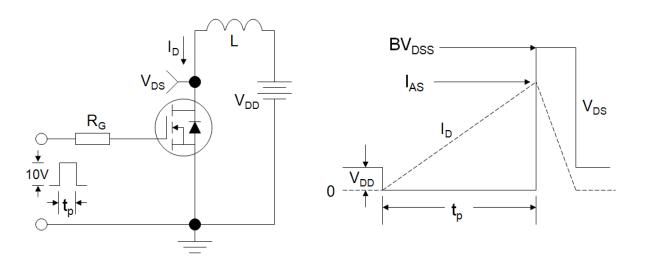
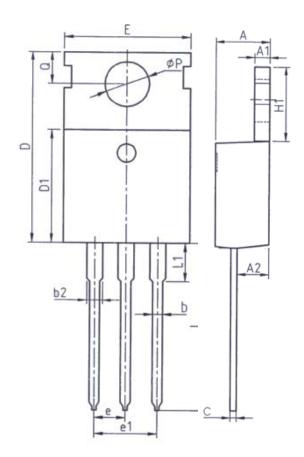


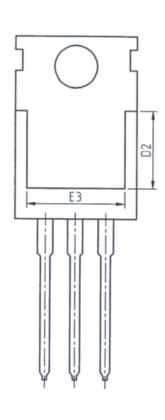
Figure C: Unclamped Inductive Switching Test Circuit and Waveform



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TO-220

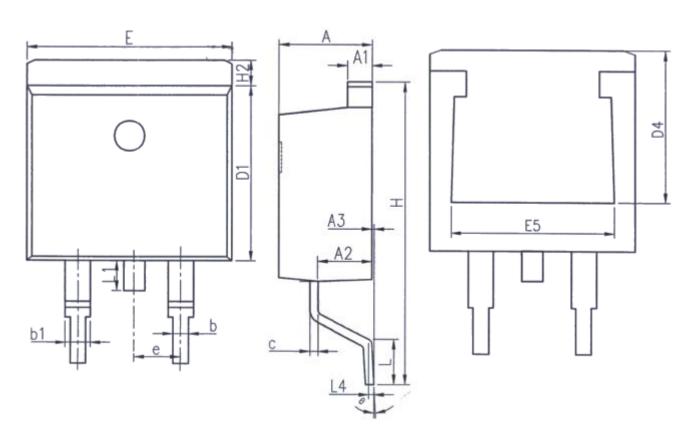




Unit: mm		
Symbol	Min.	Max.
Α	4. 37	4. 77
A1	1. 25	1. 45
A2	2. 20	2. 60
b	0. 70	0. 95
b2	1. 17	1. 47
С	0. 40	0. 65
D	15. 10	16. 10
D1	8. 80	9. 40
D2	5. 50	_

Unit: mm			
Symbol	Min. Max.		
E	9. 70	10. 30	
E3	7. 00	-	
е	2. 54BSC		
e1	5. 08BSC		
H1	6. 25	6. 85	
L	12. 75	13.80	
L1	_	3. 40	
Р	3. 40	3. 80	
Q	2. 60	3. 00	





Unit: mm			
Symbol	Min.	Max.	
Α	4. 37	4. 77	
A 1	1. 22	1. 42	
A2	2. 49	2. 89	
A3	0. 00	0. 25	
b	0. 70	0.96	
b1	1. 17	1. 47	
С	0. 30	0.53	
D1	8. 50	8. 90	
D4	6. 60	_	

Unit: mm			
Symbol	Min.	Max.	
E	9. 86	10.36	
E 5	7. 06	-	
е	2. 54BSC		
Н	14. 70	15. 50	
H2	1. 07	1. 47	
L	2.00	2. 60	
L1	1. 40	1. 70	
L4	0. 25BSC		
θ	0°	9°	



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